

Date Created: **10/13/08**
Date Issued On : **10/16/08**
PCN#: **MQ4084202**

INFORMATION ONLY NOTIFICATION

This is to inform you that a minor change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

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Implementation of change:

Expected 1st Device Shipment Date: October 18, 2008

Earliest Year/Work Week of Changed Product: 0843

Change Type Description: Label Change

Description of Change (From): Current reel and internal box labels.

Description of Change (To): To better reflect the environmental compliance status of Fairchild products, new data values are being added to the labels placed on reels and internal boxes. In addition to the RoHS compliance symbol that already exists on these labels (indicating compliance to the European Union Directive on the Restriction of Hazardous Substances, 2002/95/EC, commonly referred to as RoHS) the words "Green Component" will be added for all products that use low-halogen materials. The words "2nd Level Interconnect" will also be included on all of these labels, in compliance with J-STD-609.

Fairchild currently defines a green component according to a relatively common understanding in the electronics industry. A green component is a product that is RoHS compliant and contains less than 900 ppm bromine, 900 ppm chlorine, 1500 ppm combined bromine and chlorine and 900 ppm antimony. Fairchild is an active member of JEDEC and is working through the JEDEC committee on the development of J-STD-709, which will define low-halogen components. Fairchild is ready to recognize and comply with J-STD-709 when the final version is issued.

These changes are improvements to our labels only and will have absolutely no effect on the product itself.

These new labels will be phased in over time. Existing warehouse inventory is not being re-labeled as a result of this change. Therefore, customers may receive a mixture of new and old labels until existing inventories have been exhausted.

Implementation of the new labels has begun and shipments may occur immediately.

Reason for Change:

1. Compliance with the latest revision of J-STD-609.
2. Provide identification of green components.

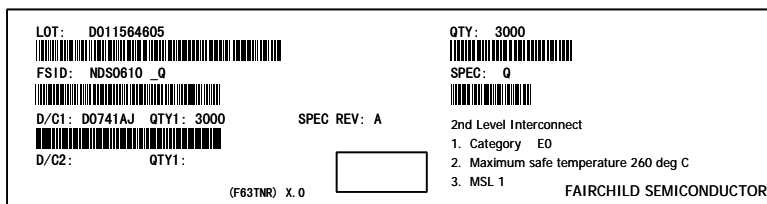
Change From:

No label to identify green components.

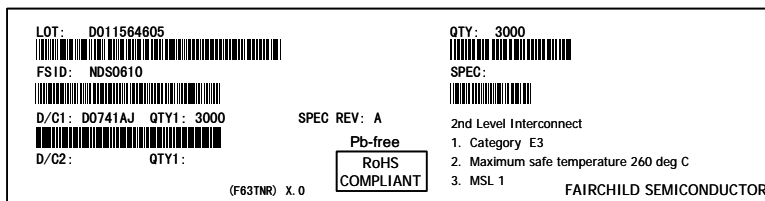
Change To:

Examples of the new labels are shown below:

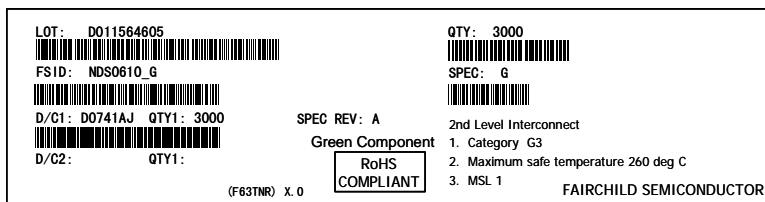
1. Parts that use SnPb plating and are not RoHS compliant would not include any reference to Pb-free or RoHS compliance. The label would look something like this:



2. Parts that are RoHS compliant would have the RoHS compliance "box" and the words "Pb-free". The label would look something like this:



3. Parts that are RoHS compliant AND use only low-halogen materials in their construction would have the RoHS compliance "box" and the words "Green Component". The label would look something like this:



In some cases, as a result of limited space on existing labels, an additional label may be required.

In addition to including the words “Green Component”, the 2nd Level Interconnect Category will change as follows:

2nd Level Interconnect Category			
Standard Component	Green Component	Abbreviation	Description
E0	Not Possible	SnPb	Terminal or lead plating containing intentionally added lead (Pb)
E1	G1	SnAgCu	SnAgCu (shall not be included in category e2)
E2	G2	Sn Alloys	Sn alloys with no Bi or Zn, excluding SnAgCu
E3	G3	Sn	Pure tin (matte, bright, hot dip, etc.)
E4	G4	Precious M	Precious metals (e.g. Ag, Au, NiPd, NiPdAu, Au/Ni, etc.) (no Sn)
E5	G5	SnZn or Sn	SnZn, SnZnx (no Bi)
E6	G6	cntns Bi	Contains Bi
E7	G7	lowtmp sol	Low temperature solder (</=150 deg C) containing Indium (no Bi)
E9	G9	bare die	Wafer and/or die level products (NOT CSP) that are Pb-Free.

Product Id Description: Affected FSIDs :

All Fairchild products are affected by this change.